



(51) International Patent Classification:

H01R 12/71 (2011.01) G06F 1/16 (2006.01)
H01R 13/6581 (2011.01)

(21) International Application Number:

PCT/US2024/046259

(22) International Filing Date:

11 September 2024 (11.09.2024)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

63/585,631 27 September 2023 (27.09.2023) US
18/581,357 19 February 2024 (19.02.2024) US

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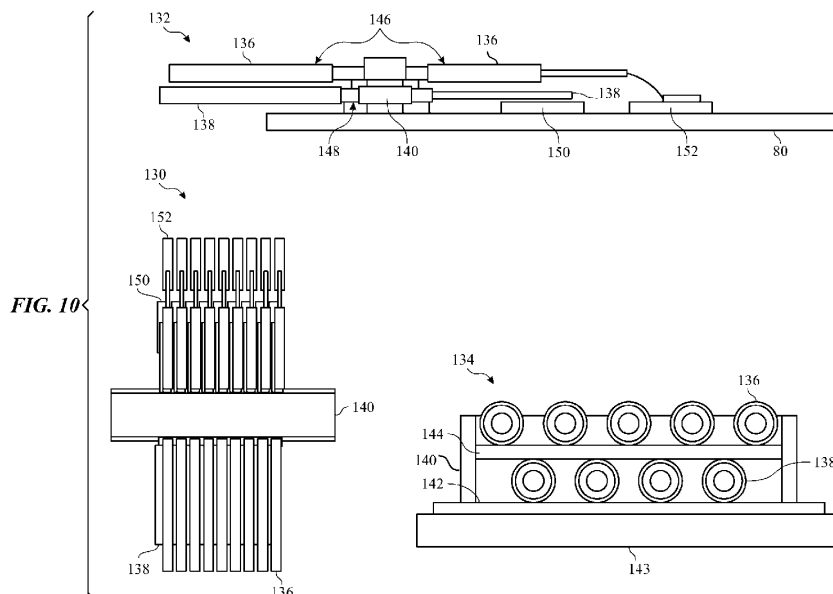
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(81) Designated States (*unless otherwise indicated, for every
kind of national protection available*): AE, AG, AL, AM,
AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ,
CA, CH, CL, CN, CO, CR, CU, CV, CZ, DE, DJ, DK, DM,
DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT,

(54) Title: COMPACT INTERFACE THROUGH HINGE CONNECTOR



(57) Abstract: Electronic devices and methods include a first electronic device that includes a printed circuit board and a quad plug connector coupled to a first surface of a printed circuit board. A first set of wires is coupled to a second surface of the printed circuit board, and the first set of wires are parallel to each other and are located on a first plane. A second set of wires is coupled to the second surface of the printed circuit board. The second set of wires are parallel to each other and are located on a second plane. The first and second planes are each parallel to each other and to the second surface of the printed circuit board. Moreover, the first set of wires is vertically above the second set of wires.

[Continued on next page]

HN, HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE, KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, MG, MK, MN, MU, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS, ZA, ZM, ZW.

(84) Designated States (*unless otherwise indicated, for every kind of regional protection available*): ARIPO (BW, CV, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SC, SD, SL, ST, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, ME, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Declarations under Rule 4.17:

- *as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))*
- *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))*

Published:

- *with international search report (Art. 21(3))*